

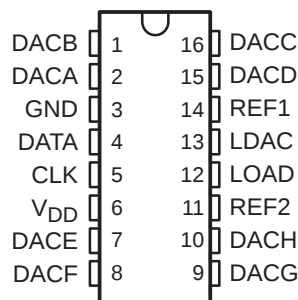
TLC5628C, TLC5628I

OCTAL 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS089E – NOVEMBER 1994 – REVISED APRIL 1997

- Eight 8-Bit Voltage Output DACs
- 5-V Single-Supply Operation
- Serial Interface
- High-Impedance Reference Inputs
- Programmable 1 or 2 Times Output Range
- Simultaneous Update Facility
- Internal Power-On Reset
- Low-Power Consumption
- Half-Buffered Output

N OR DW PACKAGE
(TOP VIEW)



applications

- Programmable Voltage Sources
- Digitally Controlled Amplifiers/Attenuators
- Mobile Communications
- Automatic Test Equipment
- Process Monitoring and Control
- Signal Synthesis

description

The TLC5628C and TLC5628I are octal 8-bit voltage output digital-to-analog converters (DACs) with buffered reference inputs (high impedance). The DACs produce an output voltage that ranges between either one or two times the reference voltages and GND and are monotonic. The device is simple to use, running from a single supply of 5 V. A power-on reset function is incorporated to ensure repeatable start-up conditions.

Digital control of the TLC5628C and TLC5628I are over a simple three-wire serial bus that is CMOS compatible and easily interfaced to all popular microprocessor and microcontroller devices. The 12-bit command word comprises eight bits of data, three DAC select bits, and a range bit, the latter allowing selection between the times 1 or times 2 output range. The DAC registers are double buffered, allowing a complete set of new values to be written to the device, then all DAC outputs are updated simultaneously through control of LDAC. The digital inputs feature Schmitt triggers for high-noise immunity.

The 16-terminal small-outline (D) package allows digital control of analog functions in space-critical applications. The TLC5628C is characterized for operation from 0°C to 70°C. The TLC5628I is characterized for operation from –40°C to 85°C. The TLC5628C and TLC5628I do not require external trimming.

AVAILABLE OPTIONS

PACKAGE		
T _A	SMALL OUTLINE (DW)	PLASTIC DIP (N)
0°C to 70°C	TLC5628CDW	TLC5628CN
–40°C to 85°C	TLC5628IDW	TLC5628IN



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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The diagram illustrates the internal architecture of the AD7792 ADC. It features a central processing block with multiple channels. Each channel includes a DAC (Digital-to-Analog Converter), a multiplier (x2), and a comparator. The DACs are connected to a common bus. The multipliers are connected to the DAC outputs. The comparators are connected to the multiplier outputs. The ADC core is connected to a Serial Interface (CLK, DATA, LOAD) and a Power-On Reset block. The outputs are labeled DAC0, DAC1, DAC2, and DAC3. The inputs are labeled REF1 and REF2. The outputs are labeled 2, 15, 7, and 10.

TERMINAL NAME	NO.	I/O	DESCRIPTION
CLK	5	I	Serial interface clock. The input digital data is shifted into the serial interface register on the falling edge of the clock applied to the CLK terminal.
DACA	2	O	DAC A analog output
DACB	1	O	DAC B analog output
DACC	16	O	DAC C analog output
DACD	15	O	DAC D analog output
DACE	7	O	DAC E analog output
DACF	8	O	DAC F analog output
DACG	9	O	DAC G analog output
DACH	10	O	DAC H analog output
DATA	4	I	Serial interface digital data input. The digital code for the DAC is clocked into the serial interface register serially. Each data bit is clocked into the register on the falling edge of the clock signal.
GND	3	I	Ground return and reference terminal
LDAC	13	I	Load DAC. When LDAC is high, no DAC output updates occur when the input digital data is read into the serial interface. The DAC outputs are only updated when LDAC is taken from high to low.
LOAD	12	I	Serial interface load control. When LDAC is low, the falling edge of the LOAD signal latches the digital data into the output latch and immediately produces the analog voltage at the DAC output terminal.
REF1	14	I	Reference voltage input to DAC A B C D. This voltage defines the analog output range.
REF2	11	I	Reference voltage input to DAC E F G H. This voltage defines the analog output range.
V _{DD}	6	I	Positive supply voltage

detailed description

The TLC5628 is implemented using eight resistor-string DACs. The core of each DAC is a single resistor with 256 taps, corresponding to the 256 possible codes listed in Table 1. One end of each resistor string is connected to GND and the other end is fed from the output of the reference input buffer. Monotonicity is maintained by use of the resistor strings. Linearity depends upon the matching of the resistor segments and upon the performance of the output buffer. Since the inputs are buffered, the DACs always present a high-impedance load to the reference sources. There are two input reference terminals; REF1 is used for DACA through DACD and REF2 is used by DACE through DACH.

Each DAC output is buffered by a configurable-gain output amplifier, that can be programmed to times 1 or times 2 gain.

On power up, the DACs are reset to CODE 0.

Each output voltage is given by:

$$V_O(\text{DACA|B|C|D|E|F|G|H}) = \text{REF} \times \frac{\text{CODE}}{256} \times (1 + \text{RNG bit value})$$

where CODE is in the range 0 to 255 and the range (RNG) bit is a 0 or 1 within the serial control word.

Table 1. Ideal Output Transfer

D7	D6	D5	D4	D3	D2	D1	D0	OUTPUT VOLTAGE
0	0	0	0	0	0	0	0	GND
0	0	0	0	0	0	0	1	$(1/256) \times \text{REF} (1+\text{RNG})$
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
0	1	1	1	1	1	1	1	$(127/256) \times \text{REF} (1+\text{RNG})$
1	0	0	0	0	0	0	0	$(128/256) \times \text{REF} (1+\text{RNG})$
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
1	1	1	1	1	1	1	1	$(255/256) \times \text{REF} (1+\text{RNG})$

data interface

With LOAD high, data is clocked into the DATA terminal on each falling edge of CLK. Once all data bits have been clocked in, LOAD is pulsed low to transfer the data from the serial input register to the selected DAC as shown in Figure 1. When LDAC is low, the selected DAC output voltage is updated when LOAD goes low. When LDAC is high during serial programming, the new value is stored within the device and can be transferred to the DAC output at a later time by pulsing LDAC low as shown in Figure 2. Data is entered most significant bit (MSB) first. Data transfers using two 8-clock cycle periods are shown in Figures 3 and 4.

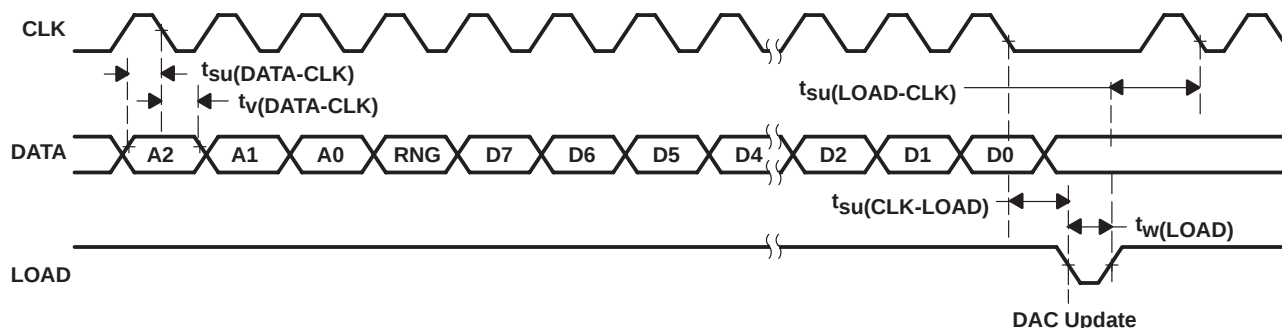


Figure 1. LOAD-Controlled Update (LDAC = Low)

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data interface (continued)

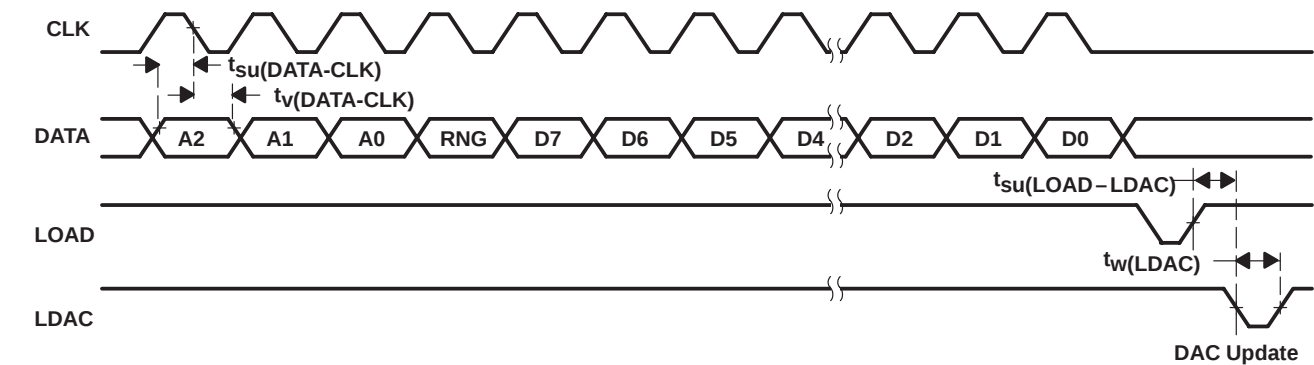


Figure 2. LDAC-Controlled Update

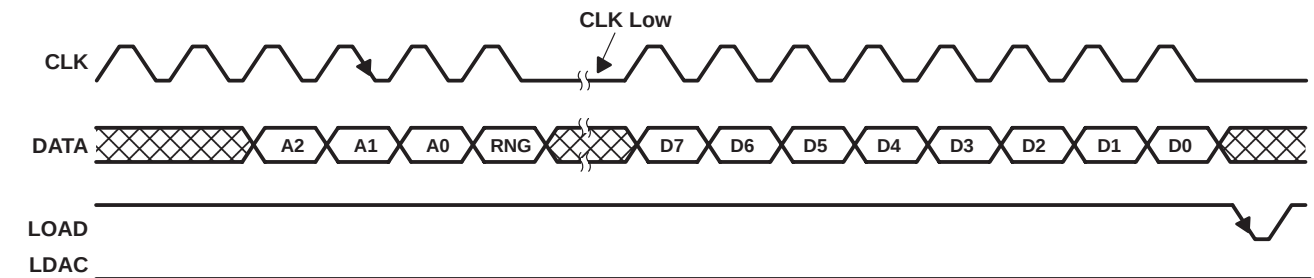


Figure 3. Load-Controlled Update Using 8-Bit Serial Word (LDAC = Low)

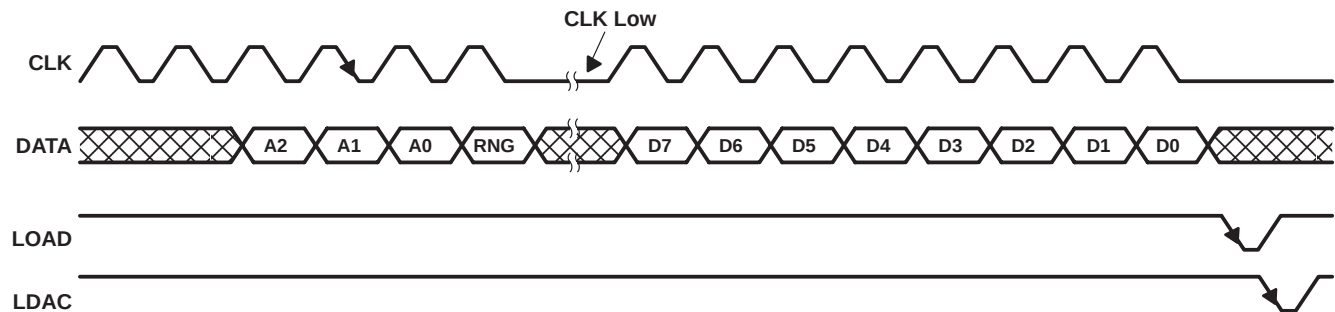


Figure 4. LDAC-Controlled Update Using 8-Bit Serial Word

Table 2 lists the A2, A1, and A0 bits and the selection of the updated DACs. The RNG bit controls the DAC output range. When RNG = low, the output range is between the applied reference voltage and GND, and when RNG = high, the range is between twice the applied reference voltage and GND.

Table 2. Serial Input Decode

A2	A1	A0	DAC UPDATED
0	0	0	DACA
0	0	1	DACB
0	1	0	DACC
0	1	1	DACD
1	0	0	DACE
1	0	1	DACF
1	1	0	DACG
1	1	1	DACH

linearity, offset, and gain error using single-end supplies

When an amplifier is operated from a single supply, the voltage offset can still be either positive or negative. With a positive offset voltage, the output voltage changes on the first code change. With a negative offset the output voltage may not change with the first code depending on the magnitude of the offset voltage.

The output amplifier, therefore, attempts to drive the output to a negative voltage. However, because the most negative supply rail is ground, the output cannot drive below ground.

The output voltage remains at 0 V until the input code value produces a sufficient output voltage to overcome the inherent negative offset voltage, resulting in the transfer function shown in Figure 5.

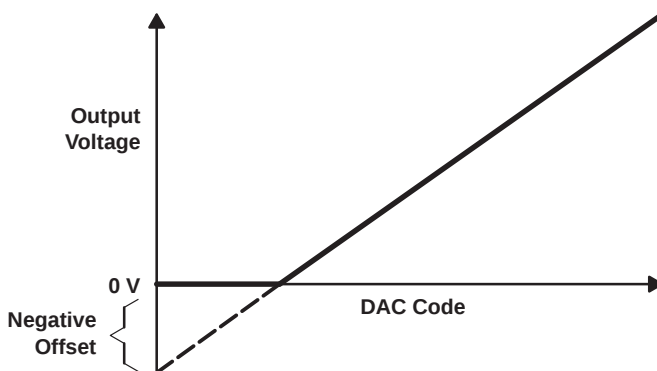


Figure 5. Effect of Negative Offset (Single Supply)

This offset error, not the linearity error, produces the breakpoint. The transfer function would have followed the dotted line if the output buffer could drive below ground.

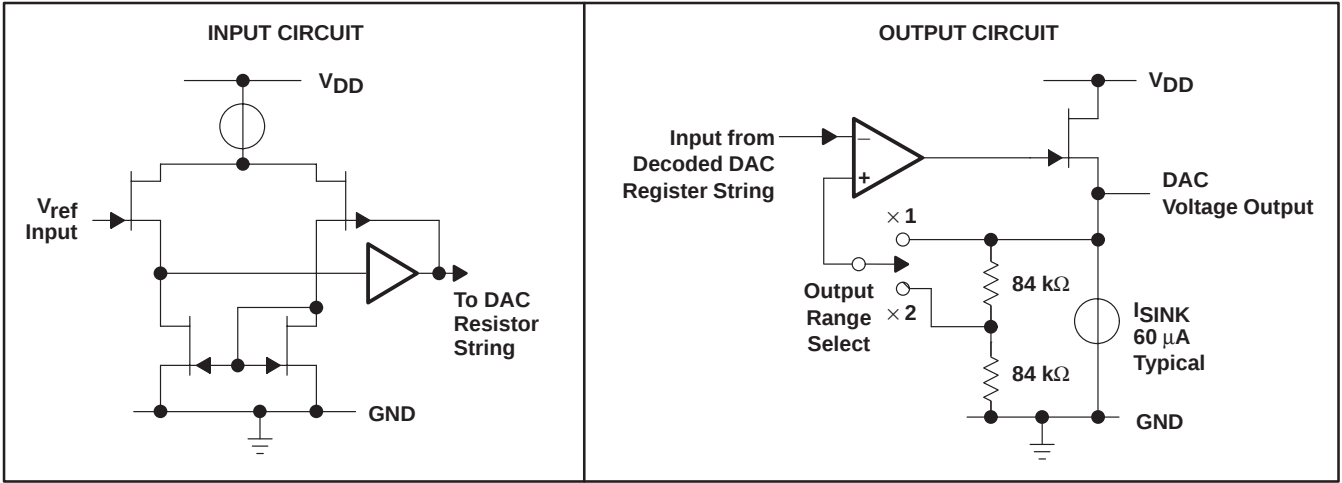
For a DAC, linearity is measured between the zero-input code (all inputs are 0) and the full-scale code (all inputs are 1) after offset and full scale are adjusted out or accounted for in some way. However, single-supply operation does not allow for adjustment when the offset is negative due to the breakpoint in the transfer function. So the linearity in the unipolar mode is measured between full-scale code and the lowest code that produces a positive output voltage.

The code is calculated from the maximum specification for the negative offset voltage.

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equivalent of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage ($V_{DD} - GND$)	7 V
Digital input voltage range, V_{ID}	$GND - 0.3 V$ to $V_{DD} + 0.3 V$
Reference input voltage range	$GND - 0.3 V$ to $V_{DD} + 0.3 V$
Operating free-air temperature range, T_A : TLC5628C	0°C to 70°C
TLC5628I	-40°C to 85°C
Storage temperature range, T_{stg}	-50°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}	4.75		5.25	V
High-level voltage, V_{IH}	0.8 V_{DD}			V
Low-level voltage, V_{IL}			0.8	V
Reference voltage, V_{ref} [A][B][C][D][E][F][G][H]			$V_{DD} - 1.5$	V
Analog full-scale output voltage, $R_L = 10 k\Omega$		3.5		V
Load resistance, R_L	10			kΩ
Setup time, data input, $t_{su}(DATA-CLK)$ (see Figures 1 and 2)	50			ns
Valid time, data input valid after $CLK\downarrow$, $t_v(DATA-CLK)$ (see Figures 1 and 2)	50			ns
Setup time, CLK eleventh falling edge to LOAD, $t_{su}(CLK-LOAD)$ (see Figure 1)	50			ns
Setup time, $LOAD\uparrow$ to $CLK\downarrow$, $t_{su}(LOAD-CLK)$ (see Figure 1)	50			ns
Pulse duration, LOAD, $t_w(LOAD)$ (see Figure 1)	250			ns
Pulse duration, LDAC, $t_w(LDAC)$ (see Figure 2)	250			ns
Setup time, $LOAD\uparrow$ to $LDAC\downarrow$, $t_{su}(LOAD-LDAC)$ (see Figure 2)	0			ns
CLK frequency			1	MHz
Operating free-air temperature, T_A	TLC5628C	0	70	°C
	TLC5628I	-40	85	°C

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electrical characteristics over recommended operating free-air temperature range, $V_{DD} = 5\text{ V} \pm 5\%$, $V_{ref} = 2\text{ V}$, $\times 1$ gain output range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{IH}	High-level input current	$V_I = V_{DD}$			± 10	μA
I_{IL}	Low-level input current	$V_I = 0\text{ V}$			± 10	μA
$I_{O(sink)}$	Output sink current	Each DAC output	20			μA
$I_{O(source)}$	Output source current		2			mA
C_i	Input capacitance			15		pF
	Reference input capacitance			15		
I_{DD}	Supply current	$V_{DD} = 5\text{ V}$			4	mA
I_{ref}	Reference input current	$V_{DD} = 5\text{ V}$, $V_{ref} = 2\text{ V}$			± 10	μA
E_L	Linearity error (end point corrected)	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 1)			± 1	LSB
E_D	Differential-linearity error	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 2)			± 0.9	LSB
E_{ZS}	Zero-scale error	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 3)	0		30	mV
	Zero-scale-error temperature coefficient	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 4)		10		$\mu\text{V}/^\circ\text{C}$
E_{FS}	Full-scale error	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 5)			± 60	mV
	Full-scale-error temperature coefficient	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 6)		± 25		$\mu\text{V}/^\circ\text{C}$
PSRR	Power supply rejection ratio	See Notes 7 and 8		0.5		mV/V

- NOTES: 1. Integral nonlinearity (INL) is the maximum deviation of the output from the line between zero and full scale (excluding the effects of zero code and full-scale errors).
2. Differential nonlinearity (DNL) is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.
3. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
4. Zero-scale-error temperature coefficient is given by: $ZSETC = [ZSE(T_{max}) - ZSE(T_{min})]/V_{ref} \times 10^6/(T_{max} - T_{min})$.
5. Full-scale error is the deviation from the ideal full-scale output ($V_{ref} - 1\text{ LSB}$) with an output load of $10\text{ k}\Omega$.
6. Full-scale error temperature coefficient is given by: $FSETC = [FSE(T_{max}) - FSE(T_{min})]/V_{ref} \times 10^6/(T_{max} - T_{min})$.
7. Zero-scale-error rejection ratio (ZSE RR) is measured by varying the V_{DD} from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the zero-code output voltage.
8. Full-scale-error rejection ratio (FSE RR) is measured by varying the V_{DD} from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the full-scale output voltage.

operating characteristics over recommended operating free-air temperature range, $V_{DD} = 5\text{ V} \pm 5\%$, $V_{ref} = 2\text{ V}$, $\times 1$ gain output range (unless otherwise noted)

	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output slew rate	$C_L = 100\text{ pF}$, $R_L = 10\text{ k}\Omega$		1		$\text{V}/\mu\text{s}$
Output settling time	To $\pm 0.5\text{ LSB}$, $C_L = 100\text{ pF}$, $R_L = 10\text{ k}\Omega$, See Note 9		10		μs
Large signal bandwidth	Measured at -3 dB point		100		kHz
Digital crosstalk	$\text{CLK} = 1\text{-MHz}$ square wave measured at DACA-DACD		-50		dB
Reference feedthrough	See Note 10		-60		dB
Channel-to-channel isolation	See Note 11		-60		dB
Reference input bandwidth	See Note 12		100		kHz

- NOTES: 9. Settling time is the time between a LOAD falling edge and the DAC output reaching full-scale voltage within $\pm 0.5\text{ LSB}$ starting from an initial output voltage equal to zero.
10. Reference feedthrough is measured at any DAC output with an input code = 00 hex with a V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz .
11. Channel-to-channel isolation is measured by setting the input code of one DAC to FF hex and the code of all other DACs to 00 hex with V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz .
12. Reference bandwidth is the -3 dB bandwidth with an input at $V_{ref} = 1.25\text{ V}$ dc + 2 V_{pp} and with a full-scale digital input code.



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PARAMETER MEASUREMENT INFORMATION

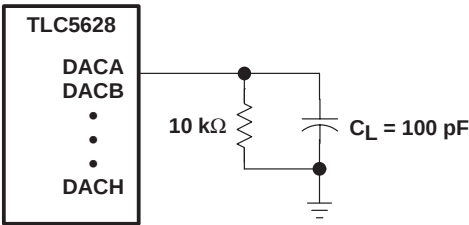


Figure 6. Slew, Settling Time, and Linearity Measurements

TYPICAL CHARACTERISTICS

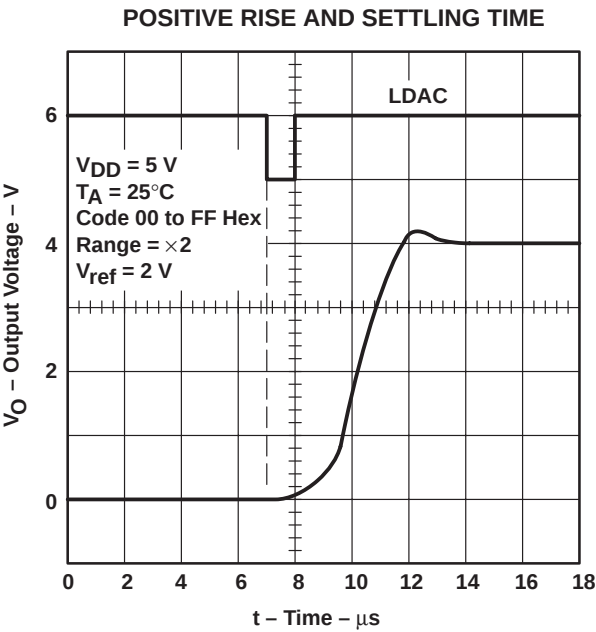


Figure 7

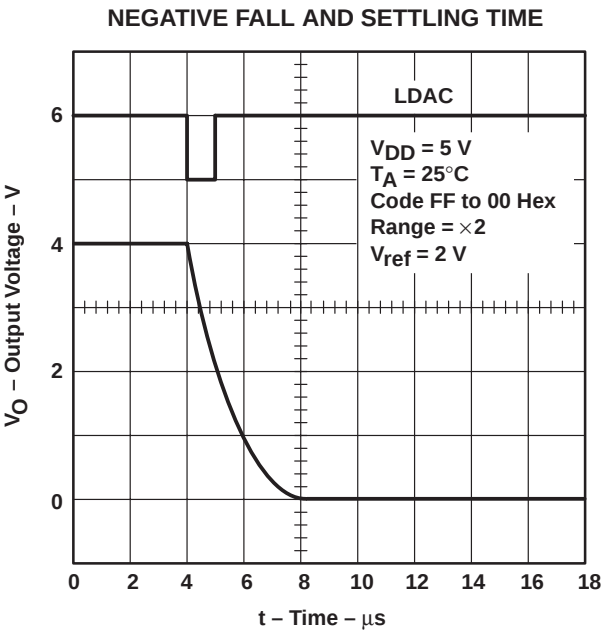


Figure 8

TYPICAL CHARACTERISTICS

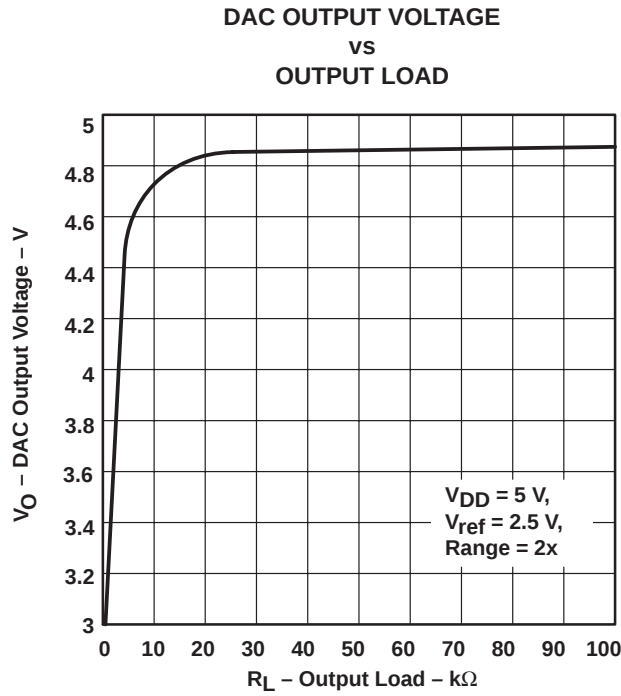


Figure 9

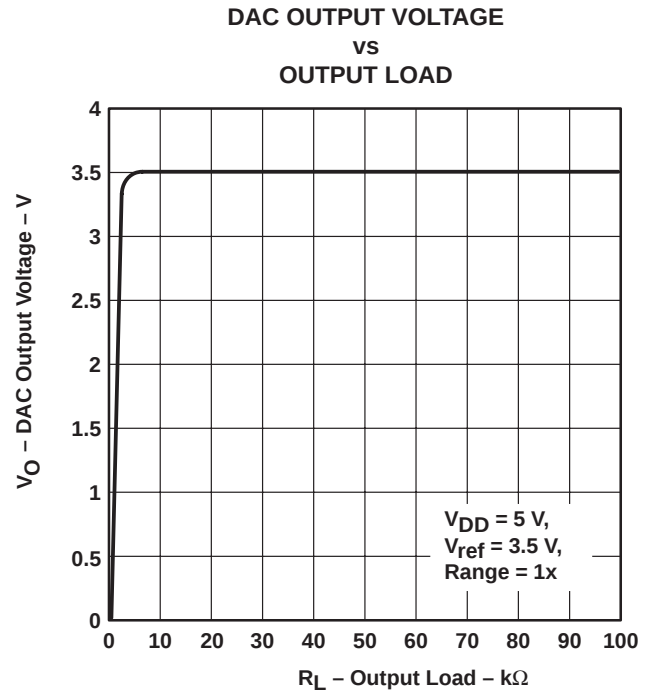


Figure 10

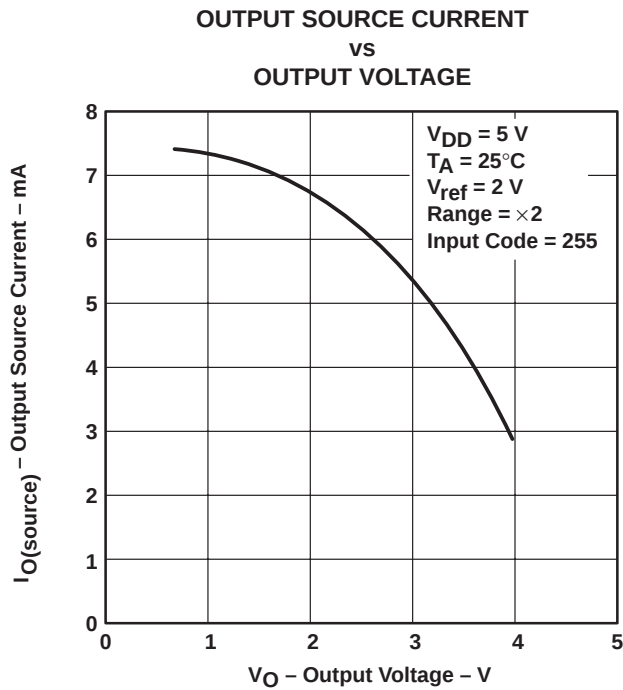


Figure 11

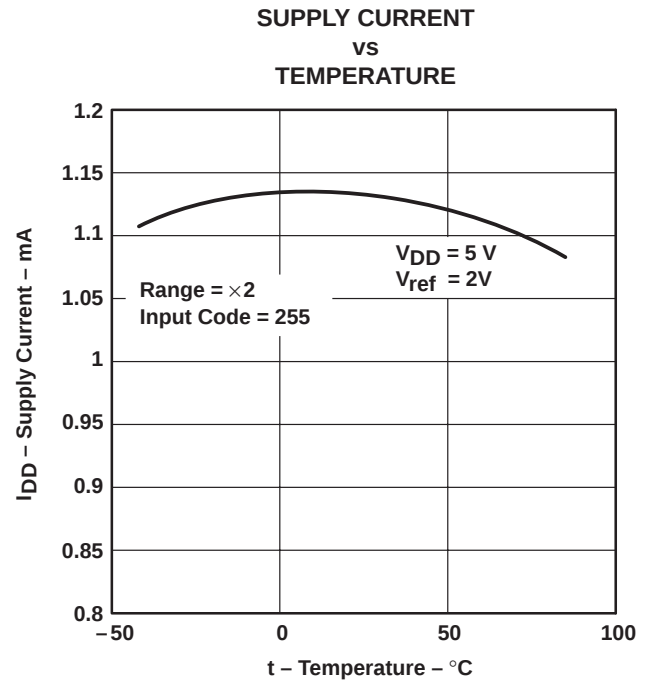


Figure 12

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TYPICAL CHARACTERISTICS

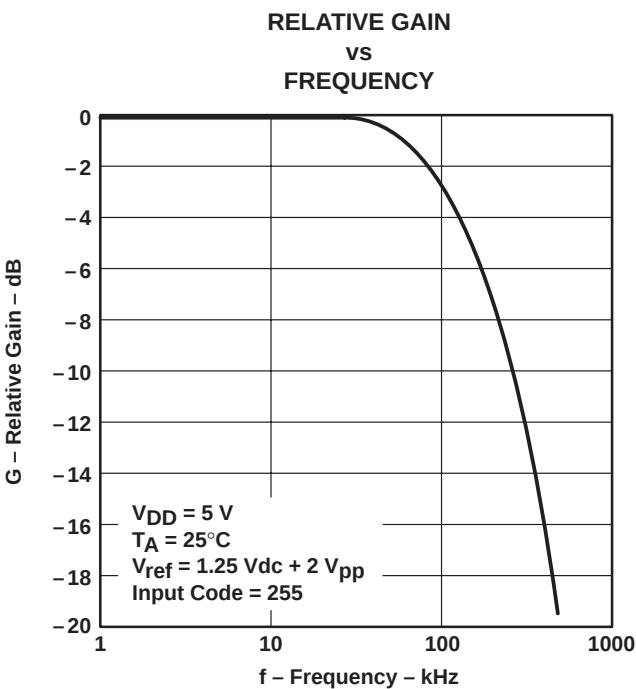


Figure 13

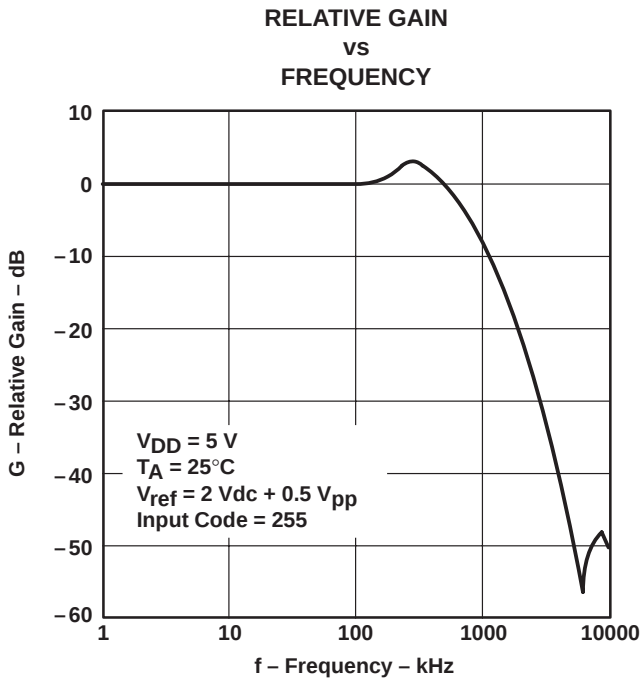
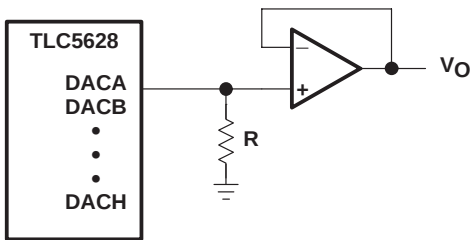


Figure 14

APPLICATION INFORMATION



NOTE A: Resistor $R \geq 10\text{ k}\Omega$

Figure 15. Output Buffering Scheme

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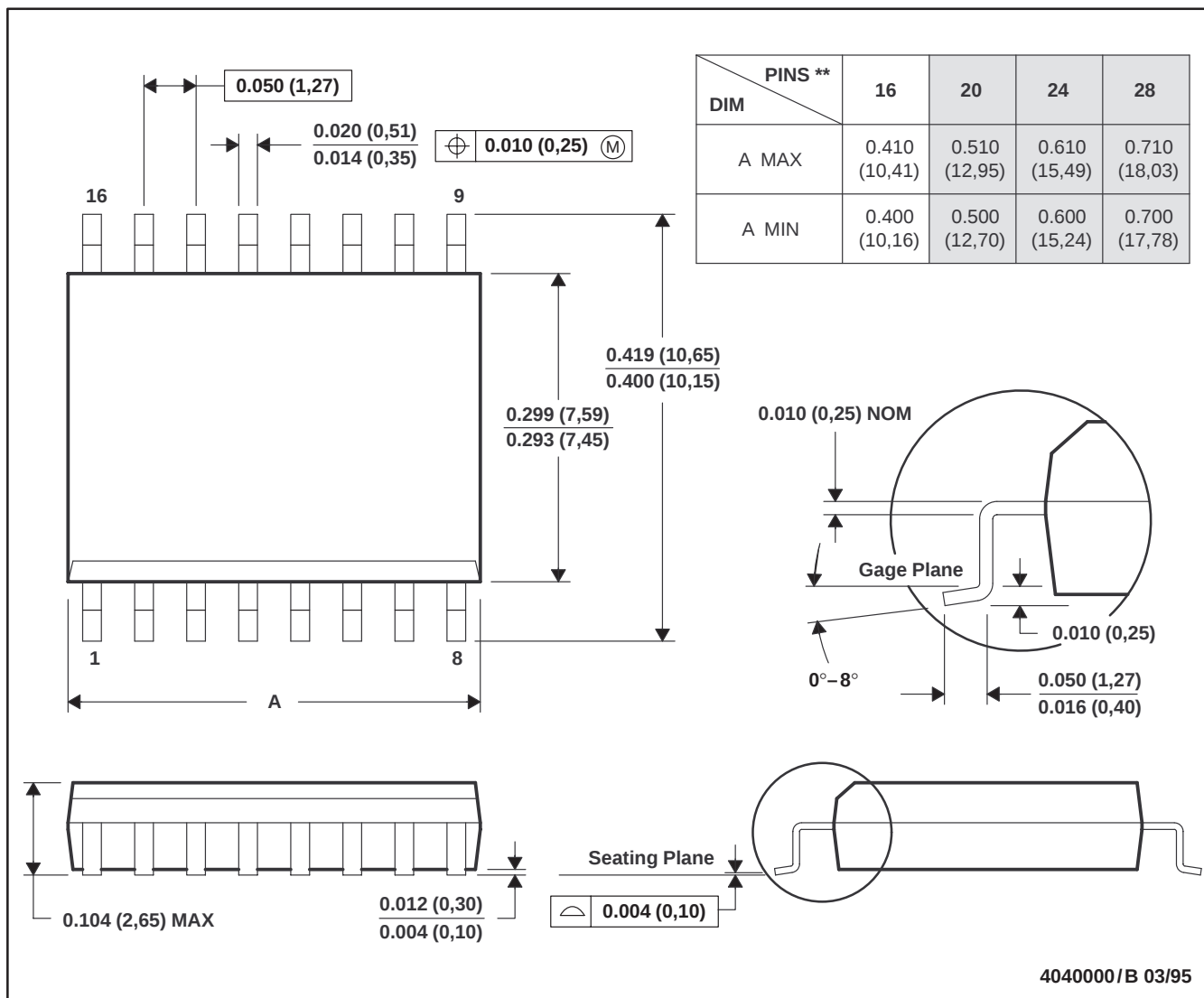
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MECHANICAL DATA

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PIN SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013

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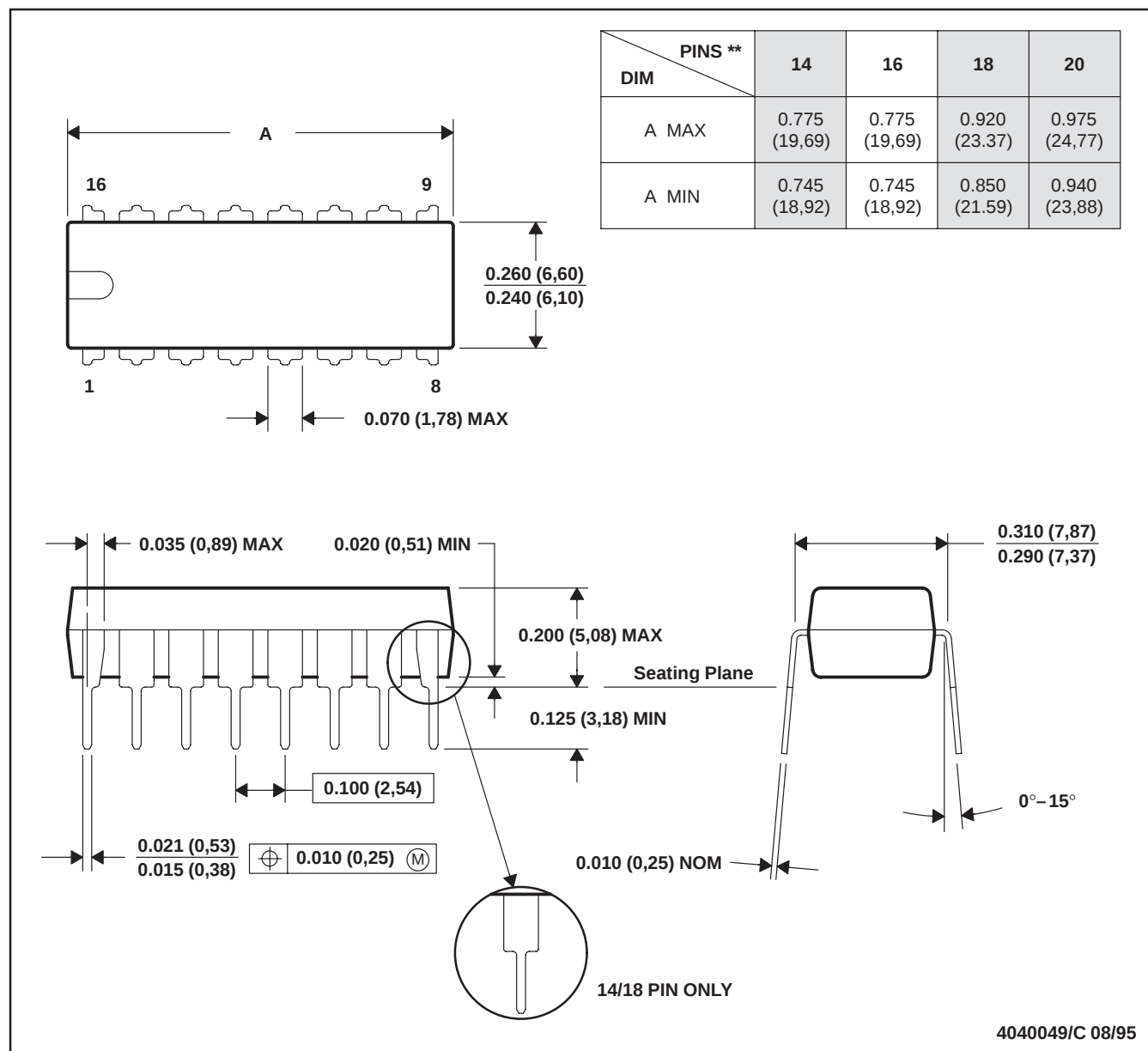
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MECHANICAL DATA

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001 (20-pin package is shorter than MS-001)

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLC5628CDW	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC5628C
TLC5628CDW.A	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC5628C
TLC5628CDWR	Active	Production	SOIC (DW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC5628C
TLC5628CDWR.A	Active	Production	SOIC (DW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC5628C
TLC5628CN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLC5628CN
TLC5628CN.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLC5628CN
TLC5628IDW	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC5628I
TLC5628IDW.A	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC5628I
TLC5628IDWR	Active	Production	SOIC (DW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC5628I
TLC5628IDWR.A	Active	Production	SOIC (DW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC5628I
TLC5628IN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	TLC5628IN
TLC5628IN.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	TLC5628IN

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC5628CDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
TLC5628IDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC5628CDWR	SOIC	DW	16	2000	350.0	350.0	43.0
TLC5628IDWR	SOIC	DW	16	2000	350.0	350.0	43.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TLC5628CDW	DW	SOIC	16	40	506.98	12.7	4826	6.6
TLC5628CDW.A	DW	SOIC	16	40	506.98	12.7	4826	6.6
TLC5628CN	N	PDIP	16	25	506	13.97	11230	4.32
TLC5628CN.A	N	PDIP	16	25	506	13.97	11230	4.32
TLC5628IDW	DW	SOIC	16	40	506.98	12.7	4826	6.6
TLC5628IDW.A	DW	SOIC	16	40	506.98	12.7	4826	6.6
TLC5628IN	N	PDIP	16	25	506	13.97	11230	4.32
TLC5628IN.A	N	PDIP	16	25	506	13.97	11230	4.32

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Last updated 10/2025